



**REPLY UNDER 37 C.F.R § 1.11(e)
EXPEDITED PROCEDURE
EXAMINING GROUP 28/3**

**EXPEDITED PROCEDURE
EXAMINING GROUP 2823**

5298-02502/PM98019C

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Sethuraman et al.

Serial No. 09/779,123

Filed: February 7, 2001

For: A PLANARIZED SEMICONDUCTOR
INTERCONNECT TOPOGRAPHY
AND METHOD FOR POLISHING A
METAL LAYER TO FORM
INTERCONNECT

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Group Art Unit: 2823

Examiner: Lee, H.

Atty. Dkt. No. 5298-02502

I hereby certify that this correspondence is being forwarded with sufficient postage as First-Class mail in an envelope addressed to: Commissioner for Patents, Box A2, Washington, DC 20231, on the date indicated below:

February 24, 2003

Date _____

Kevin L. Daffer

AMENDMENT; RESPONSE AFTER FINAL REJECTION PURSUANT TO 37 CFR § 1.116

Box AF
Commissioner for Patents
Washington, D.C. 20231

Dear Sir/Madam:

This paper is submitted in response to the Office Action mailed December 31, 200~~2~~³ to further highlight reasons why the application is in condition for allowance.

Please amend the case as follows.

IN THE CLAIMS

Please cancel claims 5, 6, 13, 14 and 16 without prejudice or disclaimer as to the subject matter recited therein. Please replace claims 1, 7, 9, 11, 15, and 17 with the amended claims below. A "marked-up" version of each amendment is included in **Attachment A**.

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